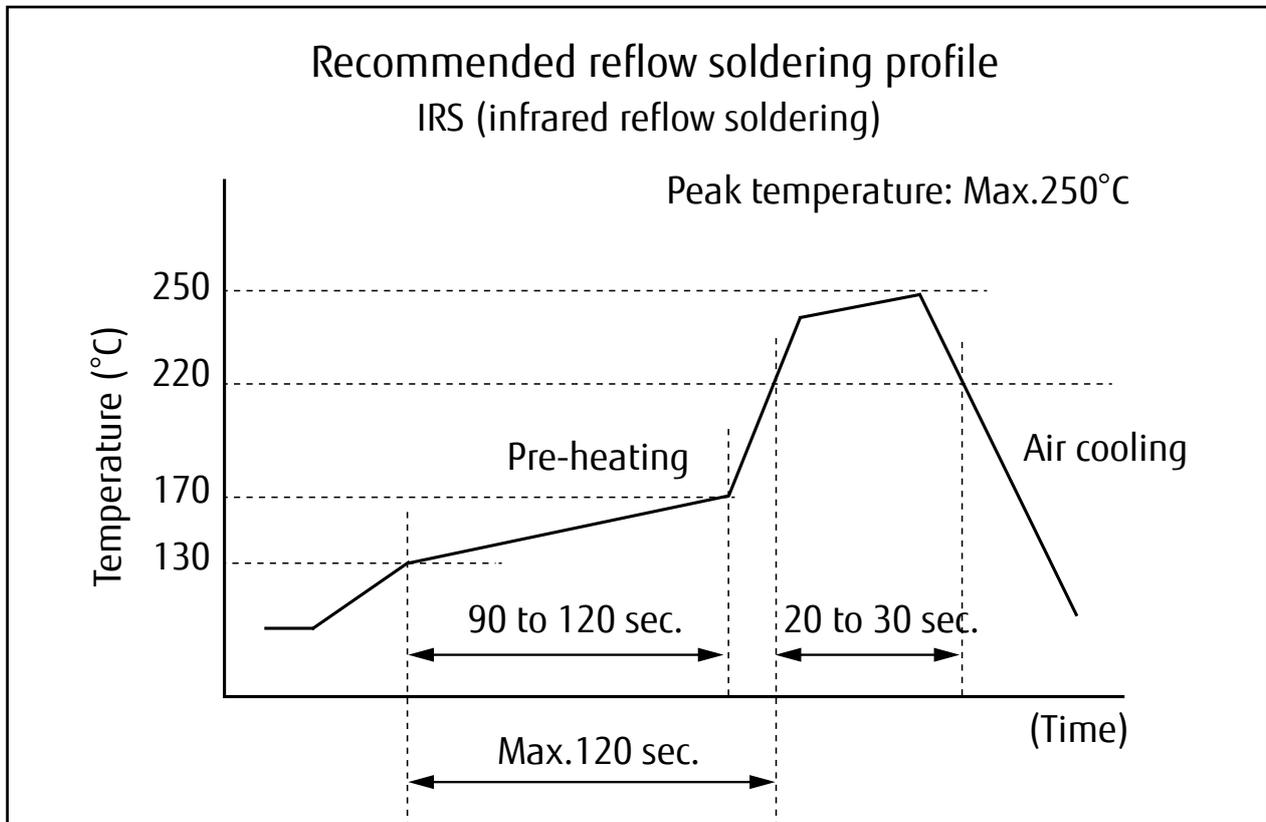


FUJITSU Component Relay

Recommended reflow solder condition



IMPORTANT NOTES

- Temperature shall be measured at PC board upper surface.
- Temperature at PC board upper surface may be changed depending on size of PC board, components mounted on the PC board and/or heating method. Please perform the confirmation test with your actual PC boards.
- This reflow solder condition is applicable only for reflow-capable relays. Do not reflow reflow-incapable relays.
- Recommended solder for assembly: Sn-3.0 Ag-0.5 Cu.